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ISSUE CLASSIFICATION	
Class	Subclass

U.S. UTILITY Patent Application

O.I.P.E. SCANNED <u>TR4</u> Q.A. <u>804</u>	PATENT DATE
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APPLICATION NO. 09/934474	CONT/PRIOR F	CLASS 451	SUBCLASS 41	ART UNIT 3723	EXAMINER SHARER
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**TITLE** **APPLICANTS**

Polishing solution; supply system, method of supplying polishing solution; apparatus for and method of polishing semiconductor substrate and method of manufacturing semiconductor device

PTO-2040  
12/99[illegible]

<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>	<b>DRAWINGS</b>		<b>CLAIMS ALLOWED</b>	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
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<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____  _____	_____ (Primary Examiner)		<b>ISSUE FEE</b>  Amount Due                      Date Paid	
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